PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
James W. Adkisson	12/14/2010
Panglijen Candra	12/14/2010
Thomas J. Dunbar	12/09/2010
Jeffrey P. Gambino	12/10/2010
Mark D. Jaffe	12/10/2010
Robert K. Leidy	12/14/2010
Yen L. Lim	12/10/2010

RECEIVING PARTY DATA

Name:	International Business Machines Corporation
Street Address:	New Orchard Road
City:	Armonk
State/Country:	NEW YORK
Postal Code:	10504

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12987402

CORRESPONDENCE DATA

Fax Number: (410)630-1656

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 410-705-6400

Email: support@gibbiplaw.com Correspondent Name: Gibb I.P. Law Firm, LLC

Address Line 1: 844 West Street Address Line 2: SUITE 100

Address Line 4: ANNAPOLIS, MARYLAND 21401

ATTORNEY DOCKET NUMBER: BUR920100070US1

PATENT **REEL: 025731 FRAME: 0135** 501423792

NAME OF SUBMITTER: Frederick W. Gibb, III Total Attachments: 4 source=BUR920100070US1_ASSIGNMENT#page1.tif source=BUR920100070US1_ASSIGNMENT#page2.tif source=BUR920100070US1_ASSIGNMENT#page3.tif source=BUR920100070US1_ASSIGNMENT#page4.tif

PATENT REEL: 025731 FRAME: 0136

IBM DOCKET NUMBER: BUR920100070US1

ASSIGNMENT

Whereas, the undersigned Inventor(s) has/have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") in:

Title of the Invention: SELF-DICING CHIPS USING THROUGH SILICON VIAS

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned Inventor ("ASSIGNOR") hereby sells, assigns, and otherwise transfers to IBM (the "ASSIGNEE"), its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned Inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to IBM, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by IBM, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made; and each undersigned Inventor agrees to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in IBM, its successors, legal representatives, and assigns, whenever requested by IBM, its successors, legal representatives, or assigns.

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[Inventor Signature Page(s) Follows]

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	Executed by Inv	entor 1	
Signature: James W	V. Adkisson	Date:	12/14/2010
	Executed by Inve	entor 2	
Signature: Panglije	n Chindra	Date:	12/14/2010
	Executed by Inve	entor 3	
Signature: Thomas	Dunbar 600753	Date:	12/9/2010
	Executed by Inve	entor 4	
Signature:	Gambino	Date:	12/10/2010
	Executed by Inve	entor 5	
Signature: Mark D.	フ <i>の</i> / .	<u>-</u> .	12/10/2010

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IBM DOCKET NUMBER: BUR920100070US1

	Executed by Inventor 6	
Signature: _	Q11 K. K. Leidy Date: 12/14/2016	
	Executed by Inventor 7	***
Signature: _	Date:	

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IBM DOCKET NUMBER: BUR920108070US1

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Signature:		Date:	
	Robert K. Leidy		
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